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(45) **Date of Patent:** Dec. 1, 2015

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- Primary Examiner* — Yu-Hsi D. Sun

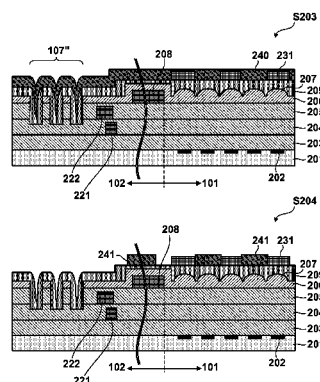
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- (57) **ABSTRACT**

- A method of manufacturing an electronic device includes forming a structure including a member, and a first film arranged on at least a surface of the member, the member including an insulating film, a passivation film arranged on the insulating film and having an upper surface, and a trench positioned from the passivation film to the insulating film; forming a second film to cover the first film; and patterning the second film by a photolithography process using a photomask. In the forming the second film, an alignment mark including a concave portion corresponding to the trench is formed in a region above the trench in the second film. In the patterning the second film, the photomask is aligned with the structure by using the alignment mark.

- (58) **Field of Classification Search**
CPC H01L 27/1469; G03F 7/20
USPC 438/64, 70
See application file for complete search history.



16 Claims, 9 Drawing Sheets

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FIG. 1

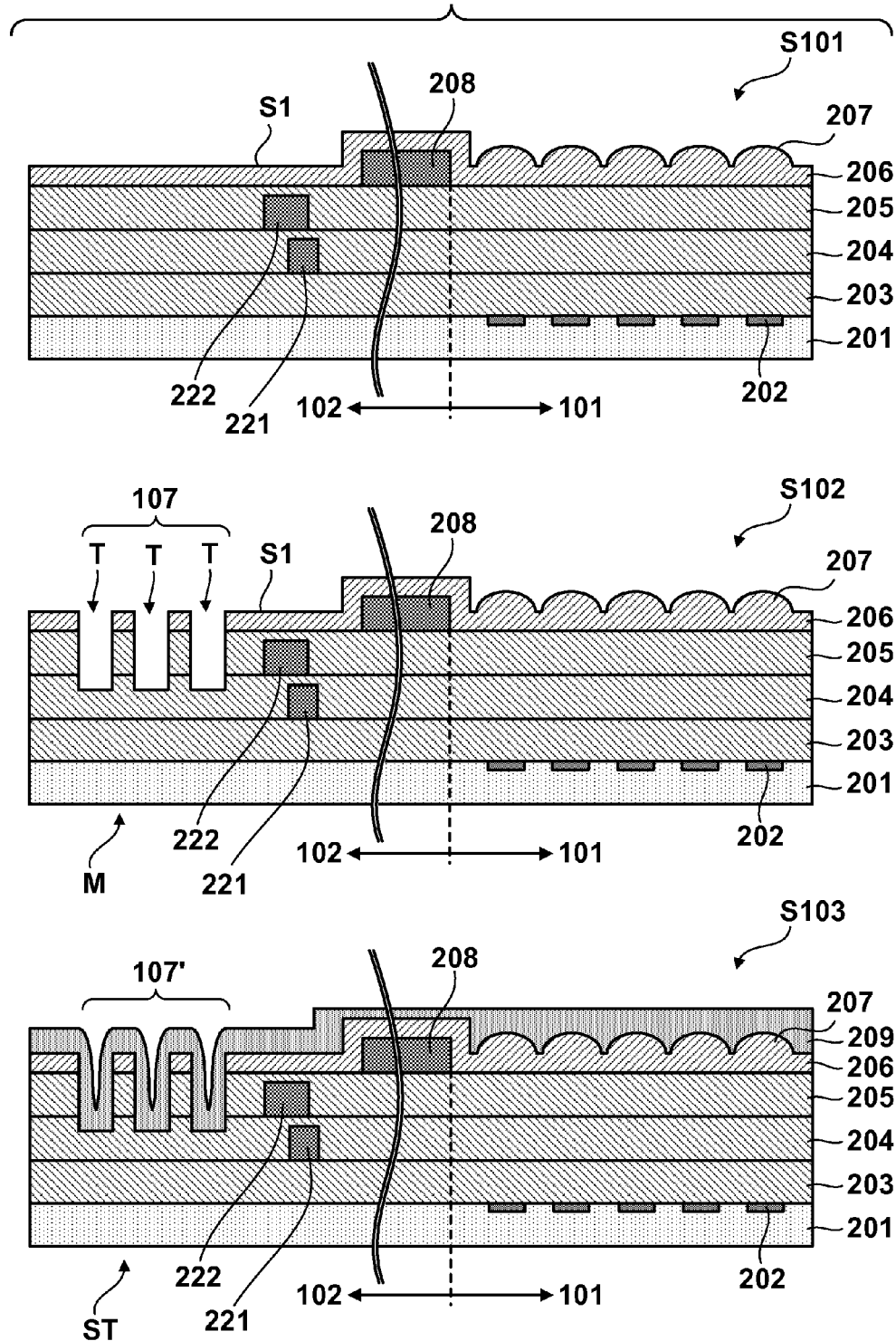


FIG. 2

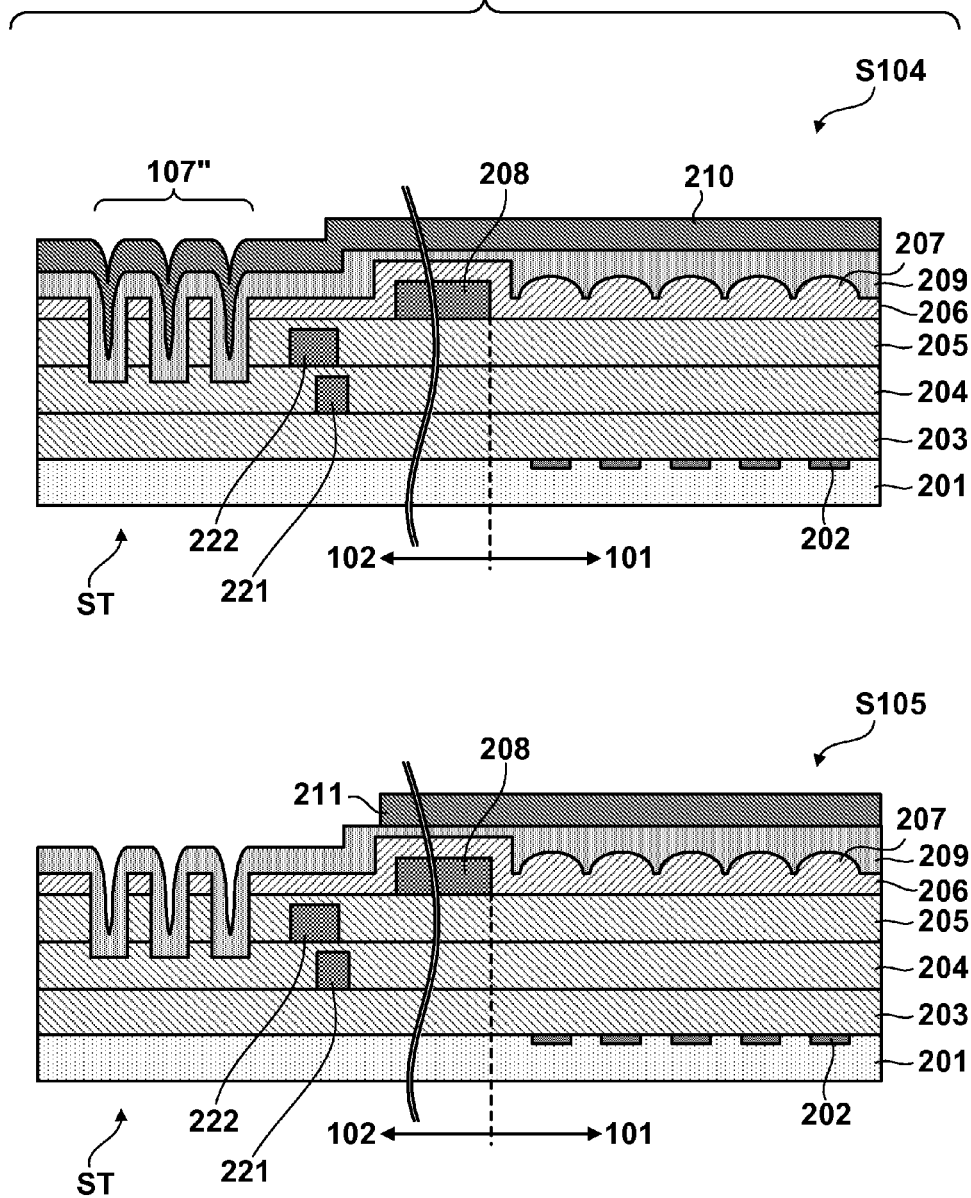


FIG. 3

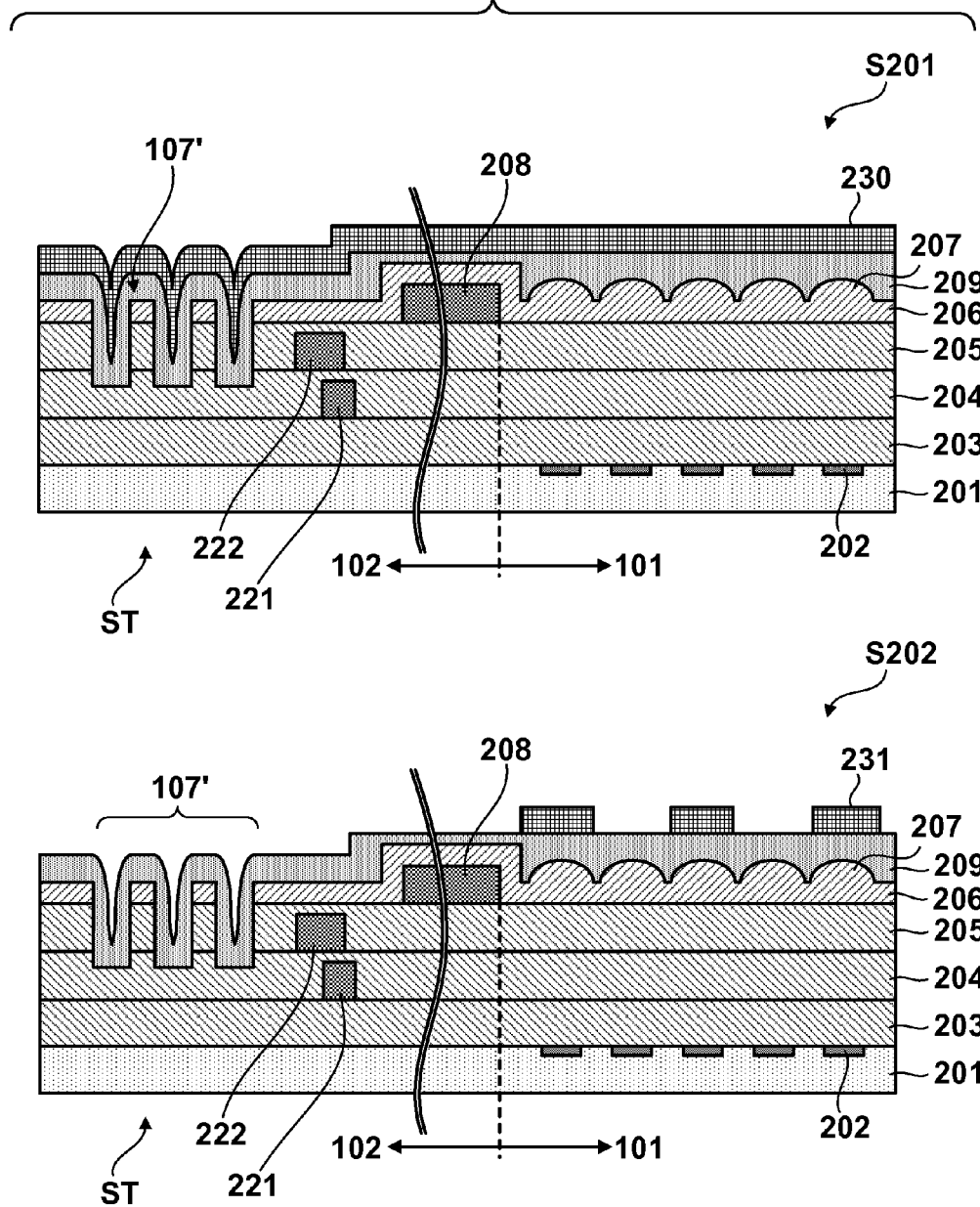


FIG. 4

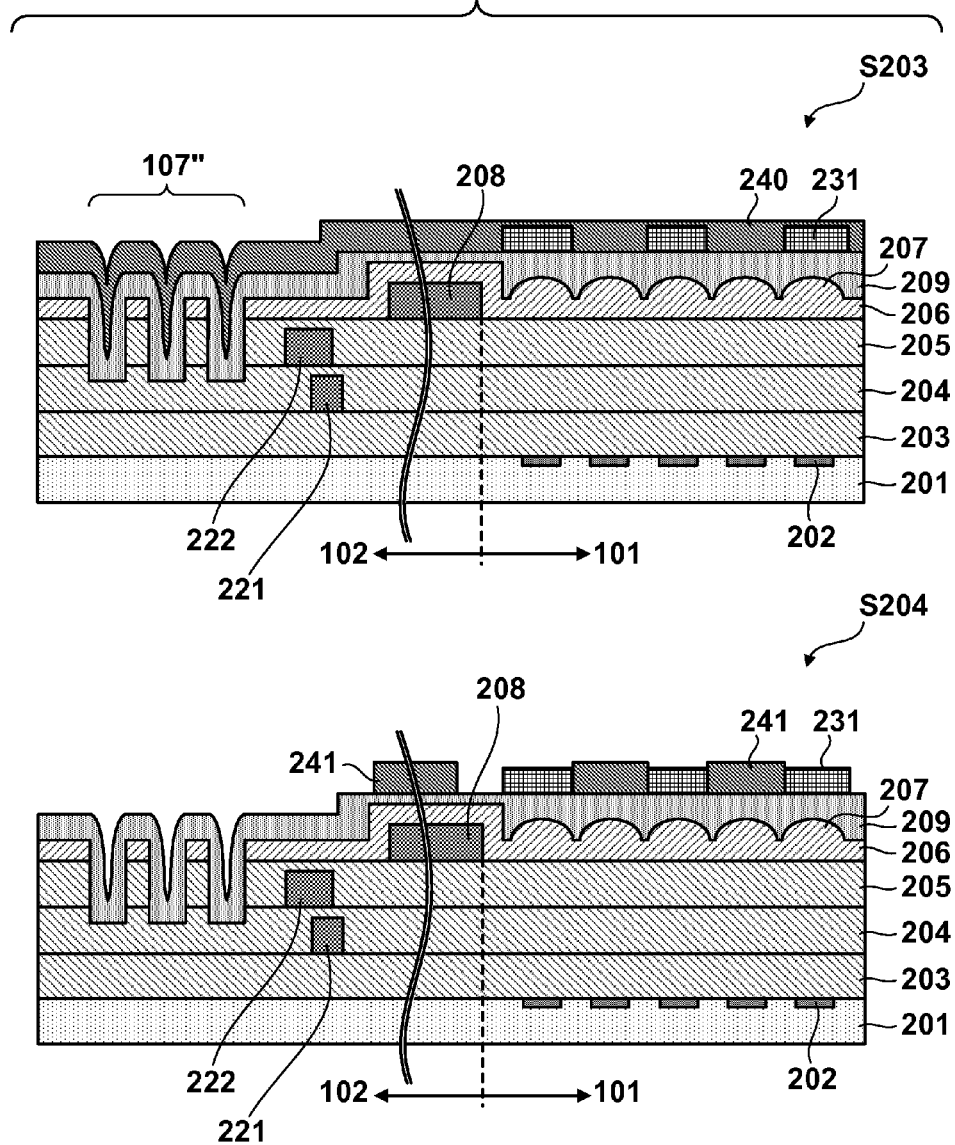


FIG. 5

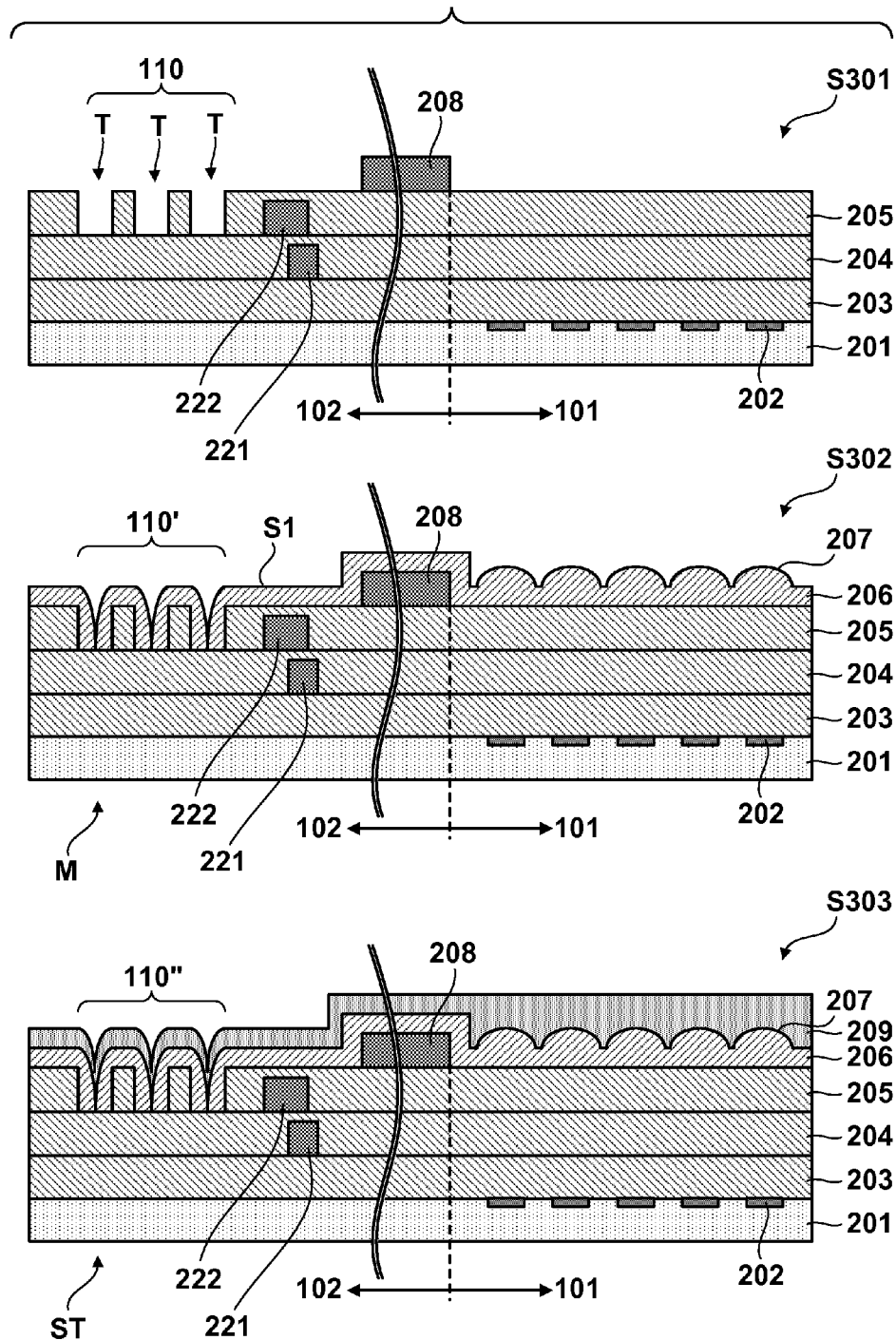


FIG. 6

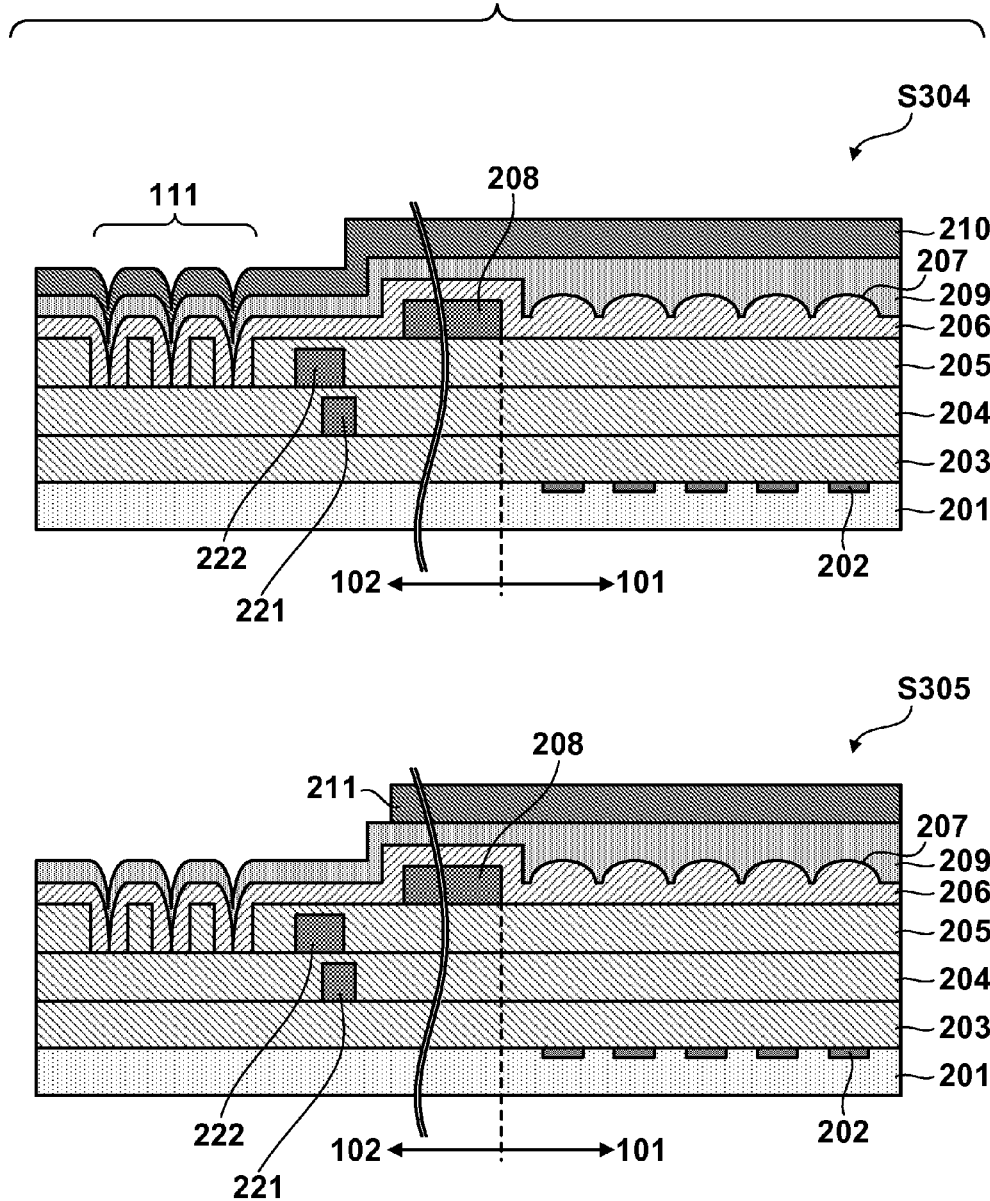


FIG. 7

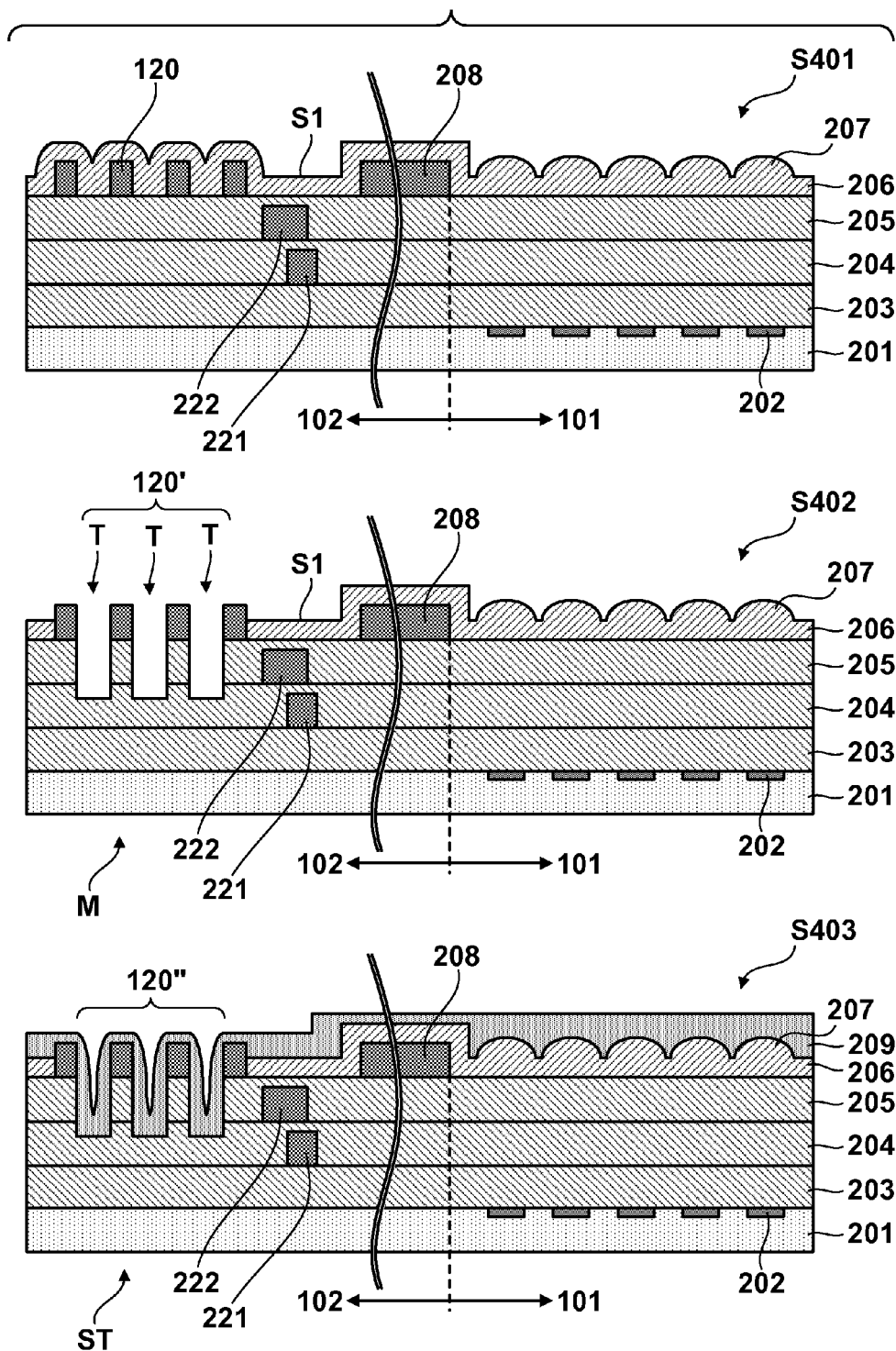


FIG. 8

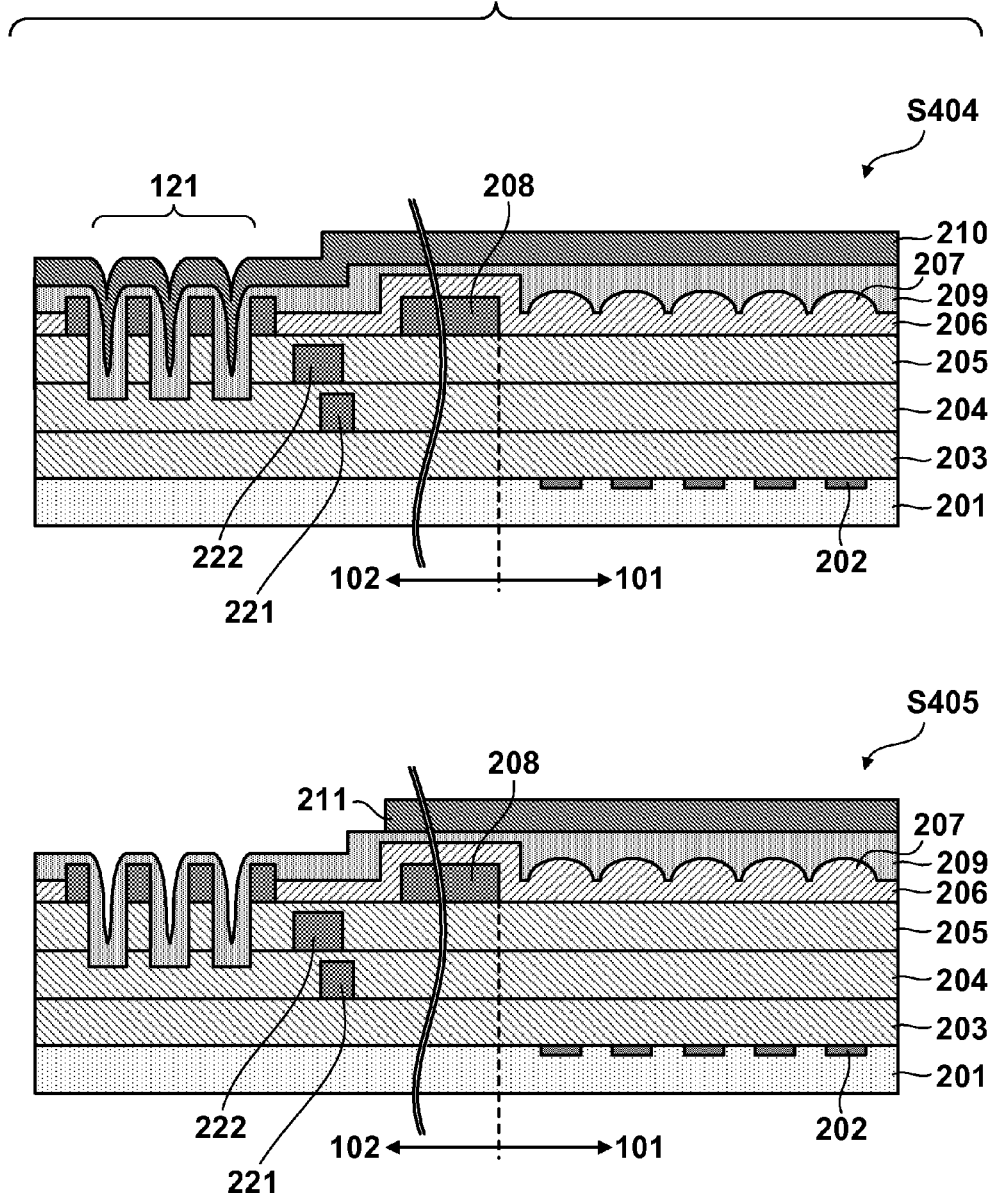
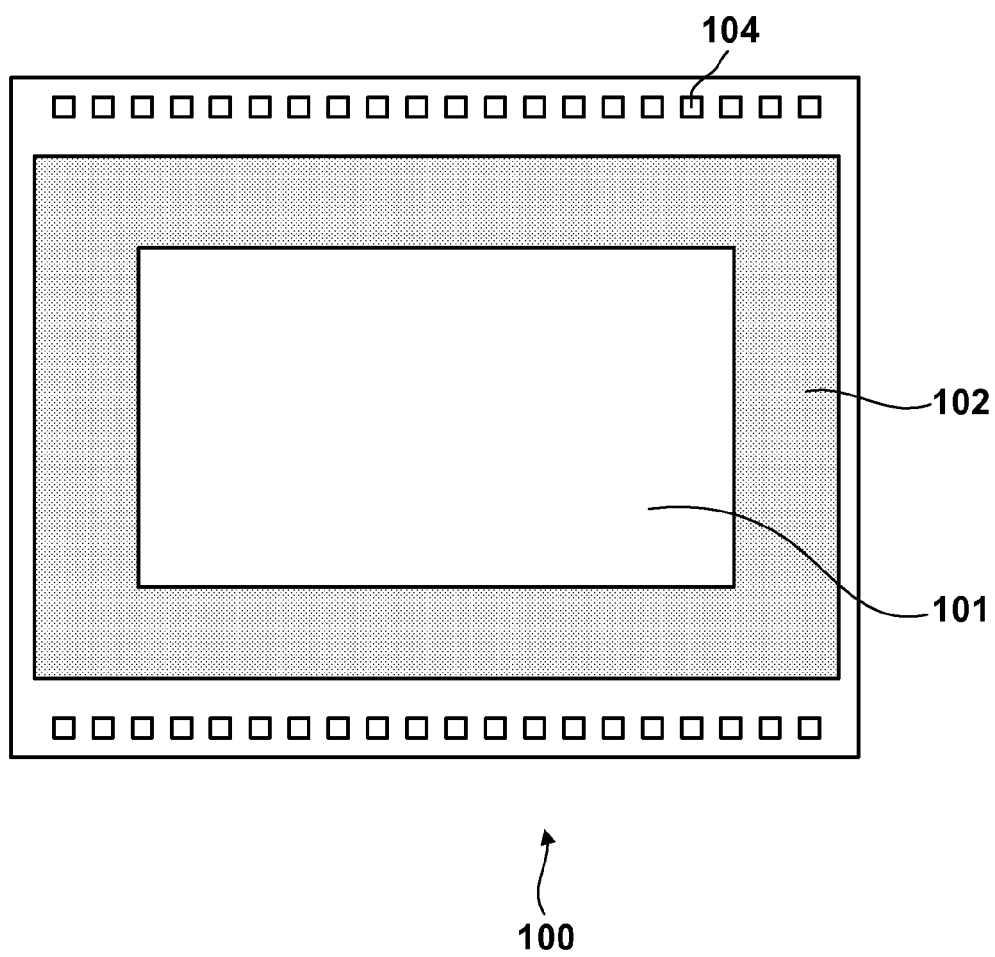


FIG. 9



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ELECTRONIC DEVICE, METHOD OF MANUFACTURING THE SAME, AND CAMERA

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention relates to an electronic device, a method of manufacturing the same, and a camera.

2. Description of the Related Art

In the manufacture of an electronic device such as a solid-state image sensing device or display device, a photolithography technique is applied to form the pattern of a blue filter, black filter, or the like. The blue filter, black filter, or the like is made of a material having low transmittance at many wavelengths of light. In alignment in the photolithography process for forming the pattern of a blue filter, black filter, or the like, an alignment mark under a film (that is, a film to be patterned) for forming the blue filter, black filter, or the like needs to be detected. However, this film has low transmittance for light used for alignment (to be referred to as alignment light hereinafter). Hence, the intensity of light reflected by the alignment mark becomes weak, and it is difficult to detect the alignment mark.

Japanese Patent Laid-Open No. 11-211908 discloses a method of forming a blue filter after forming a red filter. In this method, a red alignment mark is formed when forming a red filter, and alignment is performed with red alignment light using the red alignment mark when forming a blue filter. Japanese Patent Laid-Open No. 2007-004082 discloses a method of selectively removing a material having low light transmittance on an alignment mark and then detecting the alignment mark.

In the method disclosed in Japanese Patent Laid-Open No. 11-211908, a red alignment mark is formed when forming a red filter, and alignment is performed using the red alignment mark when forming a blue filter. Thus, a misalignment between an alignment mark under the red filter and the red alignment mark becomes an error factor in alignment for forming a blue filter.

In the method disclosed in Japanese Patent Laid-Open No. 2007-004082, a material having low light transmittance on an alignment mark is removed by the photolithography technique, so a process such as formation of a photoresist mask pattern for photolithography is necessary. That is, the technique disclosed in Japanese Patent Laid-Open No. 2007-004082 increases the number of processes and the cost.

SUMMARY OF THE INVENTION

The present invention provides a technique advantageous for alignment of a photomask.

A method of manufacturing an electronic device, comprising: forming a structure including a member, and a first film arranged on at least a surface of the member, the member including an insulating film, a passivation film arranged on the insulating film and having an upper surface, and a trench positioned from the passivation film to the insulating film; forming a second film to cover the first film; and patterning the second film by a photolithography process using a photomask, wherein in the forming the second film, an alignment mark including a concave portion corresponding to the trench is formed in a region above the trench in the second film, and wherein in the patterning the second film, the photomask is aligned with the structure by using the alignment mark.

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Further features of the present invention will become apparent from the following description of exemplary embodiments with reference to the attached drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a schematic sectional view for explaining a method of manufacturing an electronic device according to the first embodiment;

FIG. 2 is a schematic sectional view for explaining the method of manufacturing the electronic device according to the first embodiment;

FIG. 3 is a schematic sectional view for explaining a method of manufacturing an electronic device according to the second embodiment;

FIG. 4 is a schematic sectional view for explaining the method of manufacturing the electronic device according to the second embodiment;

FIG. 5 is a schematic sectional view for explaining a method of manufacturing an electronic device according to the third embodiment;

FIG. 6 is a schematic sectional view for explaining the method of manufacturing the electronic device according to the third embodiment;

FIG. 7 is a schematic sectional view for explaining a method of manufacturing an electronic device according to the fourth embodiment;

FIG. 8 is a schematic sectional view for explaining the method of manufacturing the electronic device according to the fourth embodiment; and

FIG. 9 is a schematic plan view exemplifying an electronic device.

DESCRIPTION OF THE EMBODIMENTS

The problem that detection of an alignment mark is difficult and the problem that the number of processes increases owing to detection of an alignment mark may occur when a film of a material having low light transmittance at a specific wavelength is formed on an underlying alignment mark, and also when a light-shielding film such as a metal film is formed on an underlying alignment mark.

Electronic devices manufactured according to a manufacturing method of the present invention can include electronic devices each having a color filter, such as an image sensing device (for example, a MOS image sensing device or CCD image sensing device) and a display device (for example, a liquid crystal display device). In another aspect, electronic devices manufactured according to the manufacturing method of the present invention can include all semiconductor devices each having a light-shielding pattern or metal pattern. The semiconductor devices can include, for example, an image sensing device, memory device, processing device or arithmetic device, or a device as a combination of some or all of these devices.

The present invention will be exemplarily explained through several embodiments of the present invention.

A method of manufacturing an electronic device 100 according to the first embodiment of the present invention will be explained with reference to FIGS. 1, 2, and 9. The electronic device 100 according to the first embodiment can be configured as an image sensing device applied to a blue image sensing device in a three-chip camera. The three-chip camera splits incident light into red (R), green (G), and blue (B) beams, and the red (R), green (G), and blue (B) beams are sensed by a red (R) image sensing device, green (G) image sensing device, and blue (B) image sensing device.

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As schematically shown in FIG. 9, the electronic device **100** configured as an image sensing device can include a pixel region **101**, a peripheral region **102**, and a plurality of pads **104**. The pixel region **101** includes a plurality of pixels. Each pixel includes a photoelectric converter (for example, photo-diode). The peripheral region **102** can include a circuit which drives the pixels of the pixel region **101**, and a circuit which processes signals from the pixels. The peripheral region **102** can have a light-shielding pattern. The pixel region **101** can also have a light-shielding pattern which shields a portion excluding the photoelectric converter from light.

A method of manufacturing the electronic device **100** according to the first embodiment will be explained with reference to FIGS. 1 and 2. FIGS. 1 and 2 schematically show the section of part of the pixel region **101** and the section of part of the peripheral region **102**.

A process including steps **S101**, **S102**, and **S103** is an example of a process of forming a structure **ST** including a member **M** having a surface **S1** and trenches **T** concaved from the surface **S1**, and a first film **209** arranged on at least the surface **S1** of the member **M**. In step **S101**, the structure **ST** including a semiconductor substrate **201**, insulating films **203**, **204**, and **205**, metal patterns **208**, **221**, and **222**, and a passivation film **206** is formed. The structure **ST** is made of an inorganic material. The semiconductor substrate **201** can include a plurality of photoelectric converters **202**, the diffusion regions (source and drain regions) of a transistor (not shown), and an element isolation (for example, STI: not shown). The gate electrode of the transistor (not shown) can be arranged on a gate insulating film on the semiconductor substrate **201**.

The insulating film **203** can be arranged to cover the semiconductor substrate **201** and gate electrode. The metal pattern **221** can be arranged on the insulating film **203**. The insulating film **204** can be arranged to cover the insulating film **203** and metal pattern **221**. The metal pattern **222** can be arranged on the insulating film **204**. The insulating film **205** can be arranged to cover the insulating film **204** and metal pattern **222**. A metal pattern **208** can be arranged on the insulating film **205**. The metal pattern **208** can be arranged to shield a circuit (for example, transistor) in the peripheral region **102** from light. The insulating films **203**, **204**, and **205** can be made of, for example, a silicon oxide film. The metal patterns **221**, **222**, and **208** can be made of a material mainly containing, for example, aluminum. The passivation film **206** can be arranged to cover the insulating film **205** and metal pattern **208**. The passivation film **206** can be made of, for example, a silicon nitride film. In the pixel region **101**, an interlayer lens **207** may be formed from the passivation film **206**.

In step **S102**, the passivation film **206** in the peripheral region **102** is patterned to form trenches **T** in an interlayer insulating film constituted by the insulating films **203**, **204**, and **205**. The trenches **T** can be formed by continuously etching the passivation film **206** and interlayer insulating film via the opening of a photoresist pattern (not shown) formed on the passivation film **206**. More specifically, in an etching process for exposing the pad **104** (FIG. 9) arranged on the same layer as that of the metal pattern **222**, the trenches **T** can be formed by continuously etching the passivation film **206** and the insulating films **205** and **204**. An alignment mark **107** constituted by the trenches **T** is thus formed. As a result, a member **M** having the surface **S1** and the trenches **T** concaved from the surface **S1** is obtained. In the following step, a film made of an organic material is formed.

In step **S103**, a first film **209** is formed on at least the surface of the passivation film **206**. The first film **209** is typically formed even in the trenches **T**, but does not com-

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pletely fill the trenches **T**. The first film **209** can function as a planarizing film which forms a flat surface on the passivation film **206** in the pixel region **101**. Also, the first film **209** is formed to leave an alignment mark **107** constituted by the concave portions in the region where the alignment mark **107** exists. The width and depth of the trench **T** and the thickness of the first film **209** are decided so that the alignment mark **107** exists in the region where the alignment mark **107** exists after forming the first film **209**, and an alignment mark **107** exists after forming a second film **210** (to be described later). By these processes, the structure **ST** including the member **M** having the surface **S1** and the trenches **T** concaved from the surface **S1**, and the first film **209** arranged on at least the surface **S1** of the member **M** is obtained. The first film **209** can be made of an organic material.

In step **S104**, a second film **210** is formed to cover the first film **209**. The second film **210** is made of a material having low transmittance for alignment light used in an alignment detection system mounted in an exposure apparatus. The alignment detection system can be an off-axis detection system or TTL (Through The Lens) detection system. For example, letting **T** be the average spectral transmittance in the wavelength range of alignment light, the second film **210** can be a film made of a material having $T \leq 5\%$. When an He—Ne laser generates alignment light, the wavelength of the alignment light is around 633 nm. When the He—Ne laser is used, a material having the average transmittance **T** of 5% or less is, for example, a blue photoresist or black photoresist. In the first embodiment, the He—Ne laser generates alignment light, and the second film **210** is a blue photoresist film.

After forming the second film **210**, the alignment mark **107** constituted by the concave portions remains in the region where the alignment mark **107** exists. In the alignment detection system, alignment light irradiating the alignment mark **107** is hardly reflected at the concave portions of the alignment mark **107** in the optical axis direction of the alignment detection system. To the contrary, in the alignment detection system, alignment light irradiating the alignment mark **107** excluding the concave portions and the periphery of the alignment mark **107** is reflected in the optical axis direction of the alignment detection system. The image sensing device of the alignment detection system senses the alignment mark **107** at a satisfactorily high contrast. That is, the alignment detection system detects the position of the alignment mark **107** at a satisfactorily high accuracy by using the surface shape of the alignment mark **107**. A patterning photomask (not shown) for the second film **210** can be aligned with the structure **ST**.

In the first embodiment, the alignment mark **107** is detected not by using alignment light passing through the second film **210**, but by using the surface shape of the alignment mark **107**. It is therefore unnecessary to use alignment light passing through the second film **210** or partially remove the second film **210** in order to expose the alignment mark present below the second film **210**. Also, the second film **210** need not be thinned partially.

In step **S105**, the second film **210** is patterned by a photolithography process using a patterning photomask for the second film **210**, thereby forming a blue color filter **211**. In the photolithography process, first, the exposure apparatus detects the position of the alignment mark **107** by using the alignment detection system, and aligns the patterning photomask for the second film **210** with the structure **ST** based on the detection result. Then, the exposure apparatus exposes the second film **210** by using the photomask. A development apparatus develops the exposed second film **210**, thereby forming the blue color filter **211**.

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The alignment mark **107**, **107'**, or **107''** may be arranged on the scribe line of a semiconductor substrate for constituting the electronic device **100**, or may be arranged in the chip region. When the alignment mark **107**, **107'**, or **107''** is arranged on the scribe line, the alignment mark **107**, **107'**, or **107''** typically does not remain in the final electronic device **100**.

A method of manufacturing an electronic device **100** according to the second embodiment of the present invention will be explained with reference to FIGS. **1**, **3**, **4**, and **9**. Note that matters not mentioned in the second embodiment can comply with the first embodiment. The electronic device **100** according to the second embodiment can be configured as an image sensing device applied to a single-chip camera. The image sensing device applied to the single-chip camera includes color filters of a plurality of colors.

The manufacturing method in the second embodiment is the same as that in the first embodiment up to step **S103** (FIG. **1**). After step **S103**, in step **S201**, a film **230** is formed to cover a first film **209**. The film **230** is a green photoresist film having high transmittance for alignment light used in an alignment detection system mounted in an exposure apparatus. In step **S202**, the film **230** is patterned by a photolithography process using a patterning photomask for the film **230**, thereby forming a green color filter **231**. In the photolithography process, first, the exposure apparatus detects the position of an alignment mark **107'** under the film **230** by using the alignment detection system, and aligns the patterning photomask for the film **230** with a structure **ST** based on the detection result. Then, the exposure apparatus exposes the film **230** by using the photomask. A development apparatus develops the exposed film **230**, thereby forming the green color filter **231**. Since the green photoresist film has high transmittance for alignment light, the position of the alignment mark **107'** under the film **230** can be detected.

In the second embodiment, steps **S201** and **S202** are executed even for a red color filter (not shown). The red color filter may be formed after forming the green color filter **231**, or the green color filter **231** may be formed after forming the red color filter.

In step **S203**, a blue photoresist film is formed as a second film **240** made of a material having low transmittance for alignment light, so as to cover the first film **209**, green color filter **231**, and red color filter. After forming the second film **240**, an alignment mark **107''** constituted by concave portions remains in the region where the alignment mark **107'** exists. Similar to the first embodiment, the alignment detection system can detect the position of the alignment mark **107''** at a satisfactorily high accuracy by using the surface shape of the alignment mark **107''**. Thus, a patterning photomask for the second film **240** can be aligned with the structure **ST**.

In step **S204**, the second film **240** is patterned by a photolithography process using a patterning photomask for the second film **240**, thereby forming a blue color filter **241**. In the photolithography process, first, the exposure apparatus detects the position of the alignment mark **107''** by using the alignment detection system, and aligns the patterning photomask for the second film **240** with the structure **ST** based on the detection result. Then, the exposure apparatus exposes the second film **240** by using the photomask. A development apparatus develops the exposed second film **240**, thereby forming the blue color filter **241**.

The second embodiment is applicable not only to an image sensing device having color filters of a primary color system, but also to an image sensing device having color filters of a complementary color system.

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A method of manufacturing an electronic device **100** according to the third embodiment of the present invention will be explained with reference to FIGS. **5**, **6**, and **9**. Note that matters not mentioned in the third embodiment can comply with the first embodiment. The electronic device **100** according to the third embodiment can be configured as an image sensing device applied to a blue image sensing device in a three-chip camera.

A process including steps **S301**, **S302**, and **S303** is an example of a process of forming a structure **ST** including a member **M** having a surface **S1** and trenches **T** concaved from the surface **S1**, and a first film **209** arranged on at least the surface **S1** of the member **M**. In step **S301**, a structure including a semiconductor substrate **201**, insulating films **203**, **204**, and **205**, and metal patterns **208**, **221**, and **222** is formed. An alignment mark **110** is formed by the trenches **T**. The trenches **T** can be formed when, for example, via holes are formed in a metal pattern **222**.

In step **S302**, a passivation film **206** is formed on at least the surface of the insulating film **205**. The passivation film **206** is typically formed even in the trenches **T**, but does not completely fill the trenches **T**. In a pixel region **101**, an interlayer lens **207** may be formed from the passivation film **206**. The passivation film **206** is formed so that an alignment mark **110'** constituted by the concave portions remains in the region where the alignment mark **110** exists. The width and depth of the trench **T** and the thickness of the passivation film **206** are decided so that the alignment mark **110'** exists after forming the passivation film **206**, and an alignment mark **111** exists after forming the planarizing film **209** and a second film **210** (to be described later). By covering the trench **T** by the passivation film **206**, the side surface of the trench **T** on which the insulating film and the like are exposed can be protected.

In step **S303**, a first film **209** is formed on at least the surface of the passivation film **206**. The first film **209** is typically formed even in the concave portions of the alignment mark **110'**, but does not completely fill the concave portions. The first film **209** can function as a planarizing film which forms a flat surface on the passivation film **206** in the pixel region **101**. Also, the first film **209** is formed to leave an alignment mark **110''** constituted by the concave portions in the region where the alignment mark **110'** exists. By these processes, the structure **ST** including the member **M** having the surface **S1** and the trenches **T** concaved from the surface **S1**, and the first film **209** arranged on at least the surface **S1** of the member **M** is obtained.

In step **S304**, a second film **210** is formed to cover the first film **209**. The second film **210** is formed from a blue photoresist film made of a material having low transmittance for alignment light used in an alignment detection system mounted in an exposure apparatus. After forming the second film **210**, the alignment mark **111** constituted by the concave portions remains in the region where the alignment mark **110''** exists. Similar to the first embodiment, the alignment detection system detects the position of the alignment mark **111** at a satisfactorily high accuracy by using the surface shape of the alignment mark **111**. Thus, a patterning photomask for the second film **210** can be aligned with the structure **ST**.

In step **S305**, the second film **210** is patterned by a photolithography process using a patterning photomask for the second film **210**, thereby forming a blue color filter **211**. In the photolithography process, first, the exposure apparatus detects the position of the alignment mark **111** by using the alignment detection system, and aligns the patterning photomask for the second film **210** with the structure **ST** based on the detection result. Then, the exposure apparatus exposes the second film **210** by using the photomask. A development

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apparatus develops the exposed second film **210**, thereby forming the blue color filter **211**.

The third embodiment is applicable even to a single-chip image sensing device. In this case, color filters of a plurality of colors are arranged.

A method of manufacturing an electronic device **100** according to the fourth embodiment of the present invention will be explained with reference to FIGS. **7**, **8**, and **9**. Note that matters not mentioned in the fourth embodiment can comply with the first embodiment. The electronic device **100** according to the fourth embodiment can be configured as an image sensing device applied to a blue image sensing device in a three-chip camera.

A process including steps **S401**, **S402**, and **S403** is an example of a process of forming a structure **ST** including a member **M** having a surface **S1** and trenches **T** concaved from the surface **S1**, and a first film **209** arranged on at least the surface **S1** of the member **M**. In step **S401**, a structure including a semiconductor substrate **201**, insulating films **203**, **204**, and **205**, metal patterns **208**, **221**, and **222**, and a passivation film **206** is formed. The metal pattern **208** includes an alignment mark **120**.

In step **S402**, the passivation film **206** is partially removed to expose the alignment mark **120**, and trenches **T** are formed in an interlayer insulating film constituted by the insulating films **203**, **204**, and **205** by using the alignment mark **120** as an etching mask. An alignment mark **120'** constituted by the trenches **T** is thus formed. As a result, a member **M** having the surface **S1** and the trenches **T** concaved from the surface **S1** is obtained.

In step **S403**, a first film **209** is formed on at least the surfaces of the passivation film **206** and exposed metal pattern **208**. The first film **209** is typically formed even in the trenches **T**, but does not completely fill the trenches **T**. The first film **209** can function as a planarizing film which forms a flat surface on the passivation film **206** in a pixel region **101**. Also, the first film **209** is formed to leave an alignment mark **120''** constituted by the concave portions in the region where the alignment mark **120'** exists. The width and depth of the trench **T** and the thickness of the first film **209** are decided so that the alignment mark **120''** exists in the region where the alignment mark **120'** exists after forming the first film **209**, and an alignment mark **121** exists after forming a second film **210** (to be described later). By these processes, the structure **ST** including the member **M** having the surface **S1** and the trenches **T** concaved from the surface **S1**, and the first film **209** arranged on at least the surface **S1** of the member **M** is obtained.

In step **S404**, a second film **210** is formed to cover the first film **209**. The second film **210** is formed from a blue photoresist film made of a material having low transmittance for alignment light used in an alignment detection system mounted in an exposure apparatus. After forming the second film **210**, the alignment mark **121** constituted by the concave portions remains in the region where the alignment mark **120''** exists. Similar to the first embodiment, the alignment detection system can detect the position of the alignment mark **121** at a satisfactorily high accuracy by using the surface shape of the alignment mark **121**. A patterning photomask for the second film **210** can be aligned with the structure **ST**.

In step **S405**, the second film **210** is patterned by a photolithography process using a patterning photomask for the second film **210**, thereby forming a blue color filter **211**. In the photolithography process, first, the exposure apparatus detects the position of the alignment mark **111** by using the alignment detection system, and aligns the patterning photomask for the second film **210** with the structure **ST** based on

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the detection result. Then, the exposure apparatus exposes the second film **210** by using the photomask. A development apparatus develops the exposed second film **210**, thereby forming the blue color filter **211**.

The fourth embodiment is applicable even to a single-chip image sensing device. In this case, color filters of a plurality of colors are arranged.

As a material having low transmittance for alignment light, each of the first to fourth embodiments has exemplified a photoresist which is a photosensitive material. However, the material having low transmittance for alignment light may be a metal film. More specifically, the metal film may be formed on a structure including a member having a surface and trenches concaved from the surface, and a first film arranged on at least the surface of the member. At this time, an alignment mark having concave portions corresponding to the trenches may be formed in a region of the metal film that is positioned above the trenches.

In each of the first to fourth embodiments, the passivation film is formed. However, the passivation film may not be formed or may be formed as the first film.

In each of the first to fourth embodiments, the alignment mark made of a material having low light transmittance (material of a layer to be patterned) is removed when patterning the layer to be patterned, but may remain. The first to fourth embodiments can be combined appropriately.

While the present invention has been described with reference to exemplary embodiments, it is to be understood that the invention is not limited to the disclosed exemplary embodiments. The scope of the following claims is to be accorded the broadest interpretation so as to encompass all such modifications and equivalent structures and functions.

This application claims the benefit of Japanese Patent Application No. 2013-108372, filed May 22, 2013, which is hereby incorporated by reference herein in its entirety.

What is claimed is:

1. A method of manufacturing an electronic device, comprising:

forming a structure including a member, and a first film arranged on at least a surface of the member, the member including a metal pattern, an insulating film covering the metal pattern, a passivation film arranged on the insulating film, and a trench extending from the passivation film to the insulating film;

forming a second film to cover the first film; and patterning the second film by a photolithography process using a photomask,

wherein in the forming the second film, an alignment mark including a concave portion corresponding to the trench is formed in a region above the trench in the second film, wherein in the patterning the second film, the photomask is aligned with the structure by using the alignment mark, and

wherein the forming the structure includes etching the passivation film and the insulating film such that the trench and an opening to expose the metal pattern are formed.

2. The method according to claim 1, wherein the forming the structure includes:

forming the member; and

forming the first film on at least the surface of the member, and

wherein the forming the member includes:

forming the passivation film on the insulating film; and

forming the trench in the passivation film and the insulating film.

3. A method of manufacturing an electronic device, comprising:

forming a structure including a member, and a first film arranged on at least a surface of the member, the member including an insulating film, a trench positioned in the insulating film, and a passivation film arranged on the insulating film;

forming a second film to cover the first film; and patterning the second film by a photolithography process using a photomask,

wherein in the forming the second film, an alignment mark including a concave portion corresponding to the trench is formed in a region above the trench in the second film, and

wherein in the patterning the second film, the photomask is aligned with the structure by using the alignment mark, wherein the forming the structure includes:

forming the member; and

forming the first film on at least the surface of the member, and

wherein the forming the member includes:

forming the trench in the insulating film; and

forming the passivation film on at least the surface of the insulating film in which the trench is formed.

4. The method according to claim 3, wherein the forming the structure includes:

forming a metal pattern on the insulating film;

etching the insulating film using the metal pattern as an etching mask to form the trench; and

forming the first film on at least the surface of the insulating film in which the trench is formed.

5. The method according to claim 4, wherein the forming the structure includes, between the forming the metal pattern and the forming the trench:

forming the passivation film to cover the insulating film and the metal pattern; and

removing the passivation film from a region where the alignment mark is to be formed.

6. The method according to claim 3, wherein the member includes a semiconductor substrate on which a photoelectric converter is formed, and

wherein the second film includes a blue photoresist film for forming a blue color filter.

7. The method according to claim 6, further comprising, between the forming the structure and the forming the second film, forming a green color filter and a red color filter on the member.

8. The method according to claim 1, wherein the second film includes a metal film.

9. The method according to claim 3, wherein the passivation film includes an interlayer lens.

10. The method according to claim 1,

wherein the member includes a via hole, and

wherein the forming the structure includes forming the via hole and forming the trench.

11. The method according to claim 1, wherein:

the structure is formed from an inorganic material; and

the first film and the second film are formed from an organic material.

12. A method of manufacturing an electronic device, comprising:

forming a structure including a member including a surface, a trench concaved from the surface, and a pad, and a first film arranged on at least the surface of the member;

forming a second film to cover the first film; and

patterning the second film by a photolithography process using a photomask,

wherein the forming the structure includes exposing the pad and forming the trench,

wherein in the forming the second film, an alignment mark including a concave portion corresponding to the trench is formed in a region above the trench in the second film, and

wherein in the patterning the second film, the photomask is aligned with the structure by using the alignment mark.

13. The method according to claim 12, wherein the structure is formed from an inorganic material, and the first film and the second film are formed from an organic material.

14. The method according to claim 1, wherein the metal pattern includes a pad.

15. The method according to claim 1, wherein the trench and the opening are simultaneously formed in the etching the passivation film and the insulating film.

16. The method according to claim 1, wherein the etching the passivation film and the insulating film are performed such that the passivation film and the insulating film are continuously etched.

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